

Features

- 10.1" Fanless Design ARM Based HMI
- Rugged Designed for Industrial Usage
- Flat Front Panel Designe
- Powerful Qual Core ARM Cortex-A72 Processors
- Onboard 4GB LPDDR4 Memory
- Onboard 16GB/32GB eMMC Flash
- DC 24V Power Input With 3kV Power Isolation

Specifications

System	
Processor	Broadcom BCM2711, ARM Cortex-A72 (4x Cores, up to 1.5GHz)
System Chipset	NA
Memory	Onboard DDR4 4GB SDRAM

External IO Port	
USB	2 x USB 2.0 type A 1 x USB Download Mode, Micro USB
Serial / Parallel	1 x 2 x 5pin External Terminal Block with 2 x COM 1 x RS232(TX, RX, RTS, CTS) / 485 1 x RS232(TX, RX, RTS, CTS)
LAN	1 x GbE LAN, RJ45
Wi-Fi+Bluetooth (optional)	Onboard Wi-Fi/ Bluetooth module • 2.4 GHz, 5.0 GHz IEEE 802.11 b/g/n/ac wireless • Bluetooth 5.0, BLE.

Storage Space	
Storage	16GB/32GB eMMC Flash

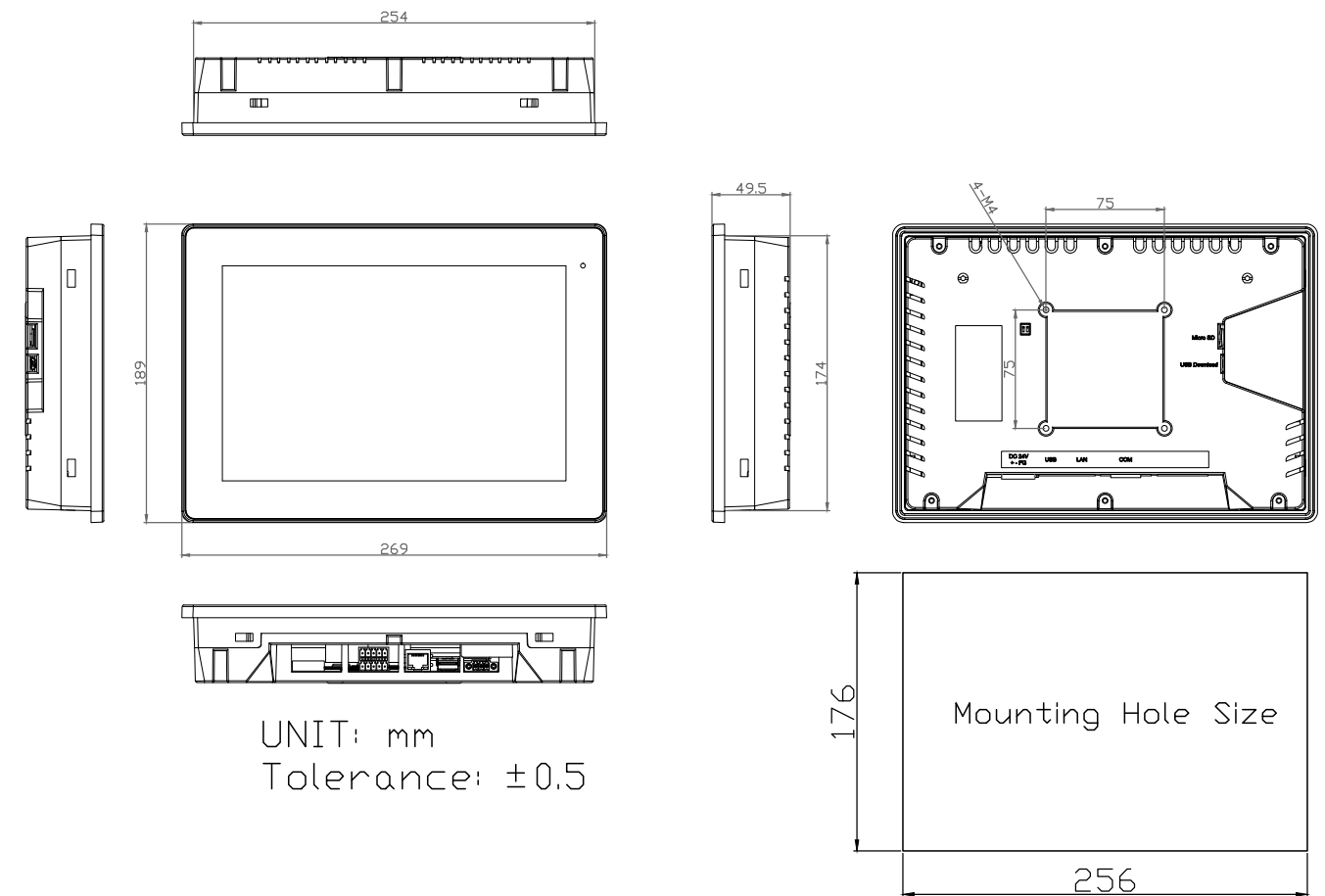
Expansion	
Expansion Slot	1 x Half / Full-size mPCIe slot with micro SIM slot
Expansion Daughter Boards	Support TB-508 series expansion boards

Display	
Display Type	10.1" TFT-LCD
Max. Resolution	1280 x 800
Max. Color	16.7M
Luminance (cd/m ²)	350
View Angle	170(H) /170(V)
Contrast	800:1
Backlight Lifetime	30,000 hrs

Touch Screen	
Type	Projected Capacitive Touch
Interface	USB
Light Transmission(%)	Over 85%

Power	
Power Input	DC 24V
Power Isolation	3kV
Power Consumption	TBD

Dimensions



Mechanical	
Construction	Industrial Plastic Chassis
Mounting	Panel Mount, VESA 75 x 75
IP Rating	IP65 compliant front bezel
Dimensions	269 x 189 x 49.5 mm
Net Weight	TBD

Environmental	
Operating Temperature	0~50°C/ -20~60°C (option)
Storage Temperature	-30~70°C
Humidity	10 to 95% @ 40°C, non- condensing
Certificate	CE/FCC Class A

Operating System Support	
Android 10 (Default) / Yocto Linux	

Ordering Information	
ARMPAC-610BP	10.1" 1280x800 fanless HMI barebone with Broadcom BCM2711 quad core ARM Cortex-A72,4GB LPDDR4 ,16/32GB eMMC,PCAP touch, 24V DC input with 3kV isolated, plastic chassis.